

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.00497	0.74	0.07548
	Doped silicon	Silicon (Si)	7440-21-3	0.66643	99.26	10.12452
		Subtotal		0.6714	100	10.2
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.0367	10.0	0.55753
	Silver alloy	Silver (Ag)	7440-22-4	0.00734	2.0	0.11151
	Lead alloy	Lead (Pb)	7439-92-1	0.32295	88.0	4.9063
		Subtotal		0.36699	100	5.57534
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.56532	100.0	8.58835
		Subtotal		0.56532	100	8.58835
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00919	0.03	0.13965
	Copper alloy	Iron (Fe)	7439-89-6	0.0337	0.11	0.51205
	Copper alloy	Copper (Cu)	7440-50-8	30.59795	99.86	464.8483
		Subtotal		30.64084	100	465.5
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.31924	100.0	4.85
		Subtotal		0.31924	100	4.85
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.3949	8.0	81.96
	Filler	Silica fused	60676-86-0	54.62332	81.0	829.845
	Metal hydroxide	Metal hydroxide		0.47205	0.7	7.1715
	Carbon Black	Carbon black	1333-86-4	0.20231	0.3	3.0735
	Polymer	Epoxy resin system		6.74362	10.0	102.45
		Subtotal		67.4362	100	1024.5
		Total		99.99999	100	1519.21369

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.